



Ai-WV01-32S Specification

版本 V1.1.2

版权 ©2025

Document Resume

Version	date	Develop/revise content	Formulate	Approved
V1.1.0	2025.7.30	First formulated	Qiao Rongxin	Guan Ning
V1.1.1	2025.8.26	Modify the serial port rate	Qiao Rongxin	Guan Ning
V1.1.2	2025.9.10	Add side dimension diagrams	Qiao Rongxin	Guan Ning

Content

1. Product Overview	4
1.1. Characteristic	5
2. Main parameters	6
2.1. Static electricity requirements	6
2.2. Electrical characteristics	7
2.3. Wi-Fi RF performance	7
2.4. BLE RF performance	8
2.5. Power consumption	8
3. Appearance dimensions	9
4. Pin Definition	11
5. Schematic	14
6. Antenna parameters	15
6.1. Antenna test prototype illustration	15
6.2. Antenna S parameters	15
6.3. Antenna gain and efficiency	16
6.4. Antenna pattern	16
7. Design Guidance	17
7.1. Application Guidance Circuit	17
7.2. Recommended PCB package size	18
7.3. Antenna layout requirements	18
7.4. Power supply	19
7.5. GPIO	20
8. Storage conditions	21
9. Reflow Oven Profile	21
10. Product packaging information	22
11. Contact Us	22
Disclaimer and Copyright Notice	23
Notice	23
Important Notice	24

1. Product Overview

Ai-WV01-32S is a Wi-Fi & BT & AIoT smart voice module developed by Shenzhen Ai-Thinker Technology Co., Ltd. The module is equipped with BL602 and VB6824 chips as core processors. Wireless support Wi-Fi The 802.11b/g/n and BLE 5.0 protocols are supported. For voice, the AI voice algorithm achieves enhanced noise reduction, highly reliable wake-up recognition rates, high-definition call quality, a richer range of offline voice control commands, faster response recognition times, and offline + online hybrid recognition capabilities . It can be widely used in AI voice products, audio and video multimedia, the Internet of Things (IoT), mobile devices, smart homes, and other fields.

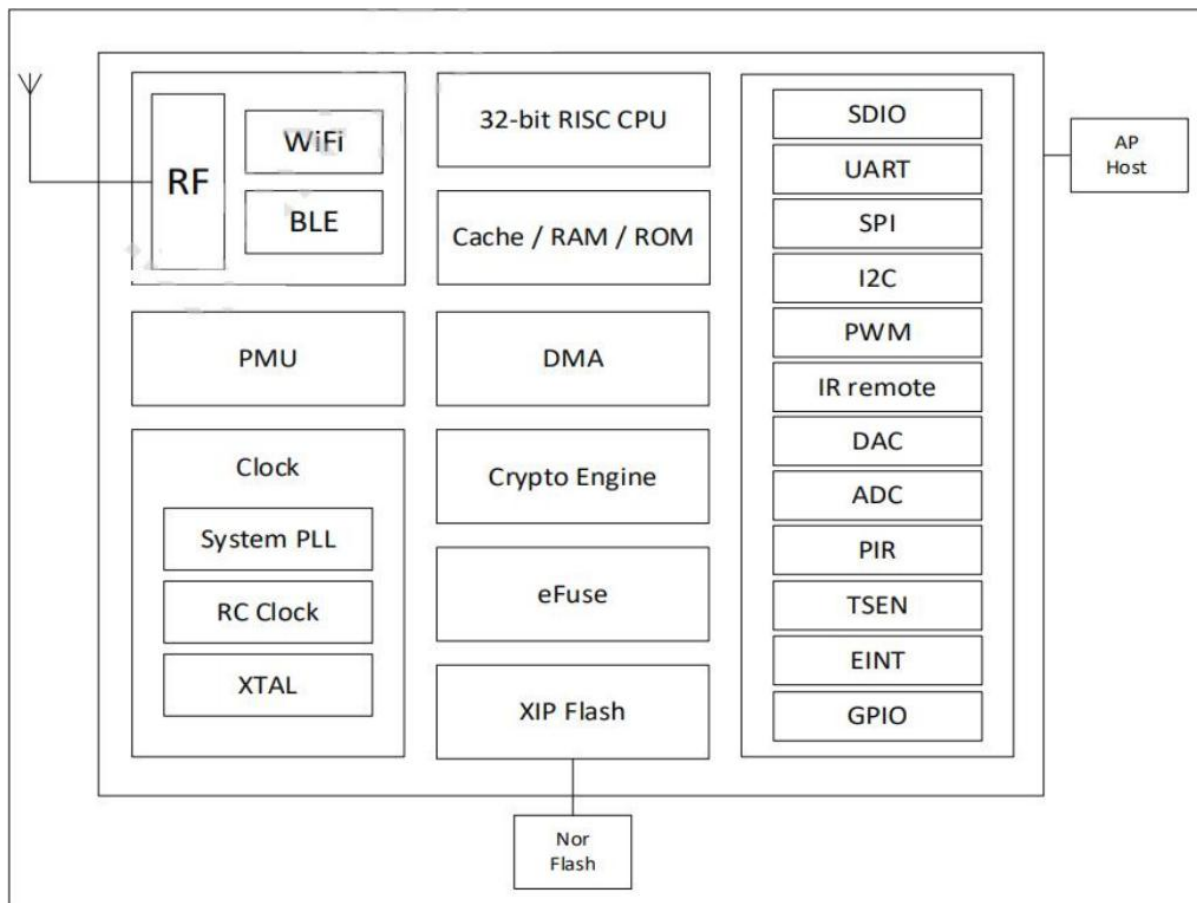


Figure 1 Main chip architecture diagram

1.1. Characteristic

- SMD-40 package
- Supports IEEE 802.11 b/g/n protocols
- Wi-Fi security supports WPS/WEP/WPA/WPA2 Personal/WPA2 Enterprise/WPA3
- Supports 20MHz bandwidth and a maximum rate of 72.2 Mbps
- Bluetooth Low Energy 5.0, Bluetooth Mesh
- Support Station + BLE mode, Station + SoftAP + BLE mode
- Support 32-bit RISC CPU, 276KB RAM
- Support SDIO, SPI, UART, I2C, IR remote, PWM, ADC, DAC, PIR , GPIO , etc.
- Support QSPI/SPI Flash on-the-fly AES decryption (OTFAD), support AES 128 CTR mode
- Support AES 128/192/256-bit encryption engine
- Support background noise suppression
- Support speech recognition (ASR) algorithm
- Support voice noise reduction algorithm
- Support multiple sleep modes, deep sleep
- Supports secondary development and integrates Windows and Linux development environments

2. Main parameters

Table 1 Description of main parameters

Model	Ai-WV01-32S
Encapsulation	SMD-40
Size	25.5*18.0*3.1(mm)
Antenna type	Onboard antenna/IPEX
Spectrum range	2400 ~ 2483.5MHz
Operating temperature	-40℃ ~ 85℃
Storage Environment	-40℃ ~ 125℃, < 90%RH
Power supply	3V3 pin voltage 3.3 V, current \geq 500mA ; 5V/DACR pin voltage 5V, current \geq 1 A
Supported interfaces	UART/GPIO/ADC/PWM/I2C/SPI
Available IO	14
Serial port rate	Default 2000000 bps
Security	WPS/WEP/WPA/WPA2 Personal/WPA2 Enterprise/WPA3
Flash	The default value is 4MByte, and the maximum supported value is 16MByte.

2.1. Static electricity requirements

Ai-WV01-32S is electrostatic sensitive device and requires special precautions when handling.



Figure 2 ESD anti-static diagram

2.2. Electrical characteristics

Table 2 Electrical characteristics

Parameter		Pins	Minimum	Typical	Maximum	Unit
Supply voltage		3V3 pin	2.7	3.3	3.6	V
		5V/DACR pin	2.5	5	6	V
I/O	VIL	-	-	-	0.3*VDDIO	V
	VI H	-	0.7 *VDDIO	-	-	V
	VOL	-	-	0.1*VDDIO	-	V
	VOH	-	-	0.9 *VDDIO	-	V
	IMAX	-	-	-	15	mA

2.3. Wi-Fi RF performance

Table 3 Wi-Fi RF performance

Describe	Typical values			Unit
Spectrum range	2400 ~ 2483.5MHz			MHz
Output power				
Model	Minimum	Typical	Maximum	unit
11n mode HT20, PA output power	-	16	-	dBm
In 11g mode, PA output power	-	17	-	dBm
In 11b mode, PA output power	-	19	-	dBm
Receive sensitivity				
Model	Minimum	Typical	Maximum	Unit
11b, 1 Mbps	-	-98	-	dBm
11b, 11 Mbps	-	-90	-	dBm
11g, 6 Mbps	-	-93	-	dBm
11g, 54 Mbps	-	-76	-	dBm
11n, HT20 (MCS7)	-	-73	-	dBm

2.4. BLE RF performance

Table 4 BLE radio frequency performance

Describe	Typical values			Unit
Spectrum range	2400 ~ 2483.5MHz			MHz
Output Power				
Rate Mode	Minimum	Typical values	Maximu	Unit
1Mbps	-	9	15	dBm
Receive Sensitivity				
Rate Mode	Minimum	Typical values	Maximu	Unit
1Mbps Sensitivity@30.8%PER	-	-96	-	dBm

2.5. Power consumption

The following power consumption data is based on a 3.3 V power supply, an ambient temperature of 25° C, and is measured using the internal voltage regulator.

- All transmit data is measured based on 100 % duty cycle in continuous transmit mode.

Table 5 Power consumption

Model	Minimum	Average	Maximum	Unit
Transmit 802.11b , 11 Mbps , POUT=+ 20	-	281	-	mA
Transmit 802.11g , 54Mbps , POUT = +1 8	-	252	-	mA
Transmit 802.11n , MCS7 , POUT = +1.7 dBm	-	266	-	mA
Receive 802.11b , packet length 1024 bytes	-	94	-	mA
Receive 802.11g , packet length 1024 bytes	-	94	-	mA
Receive 802.11n , packet length 1024 bytes	-	94	-	mA

3. Appearance dimensions

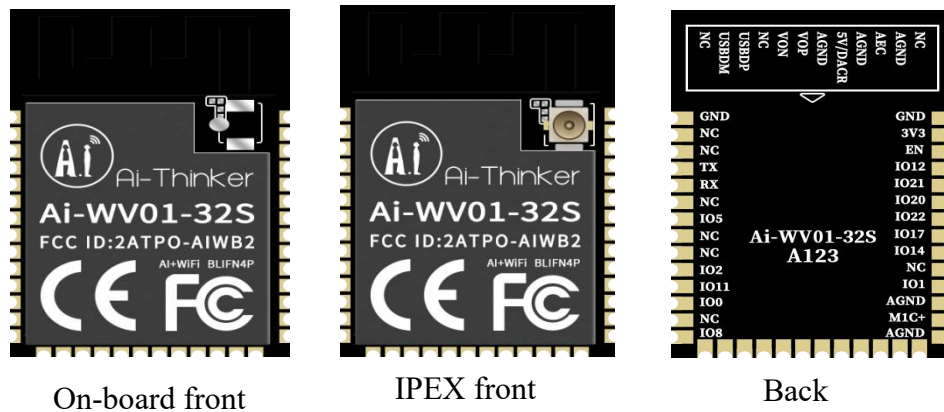


Figure 3 Appearance (rendering is for reference only, the actual product shall prevail)

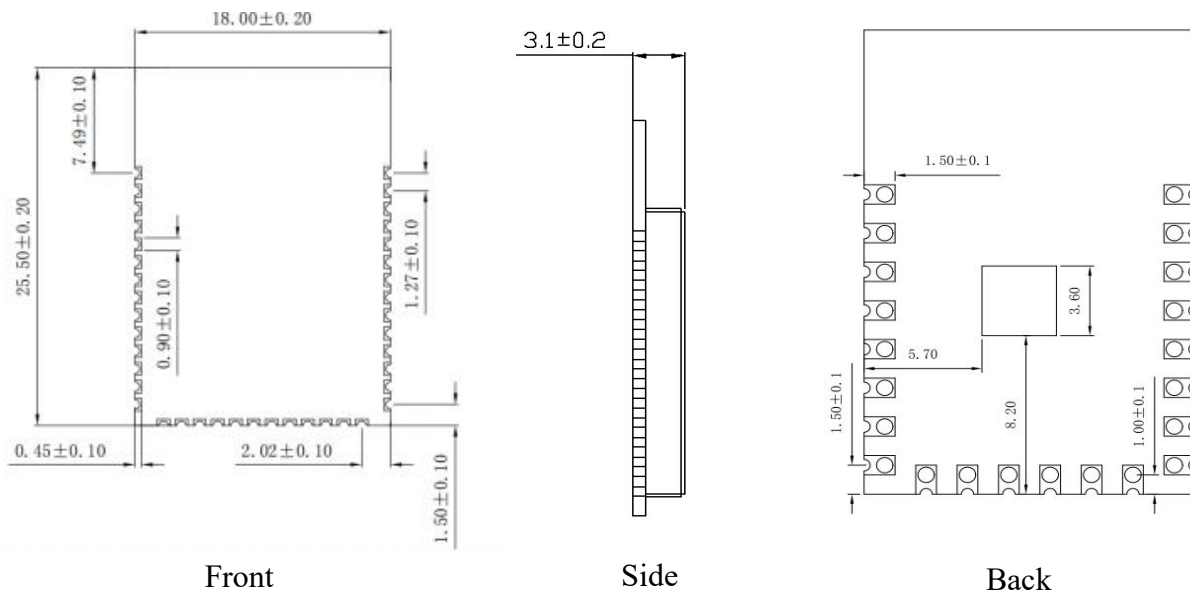


Figure 4 Dimensional drawing

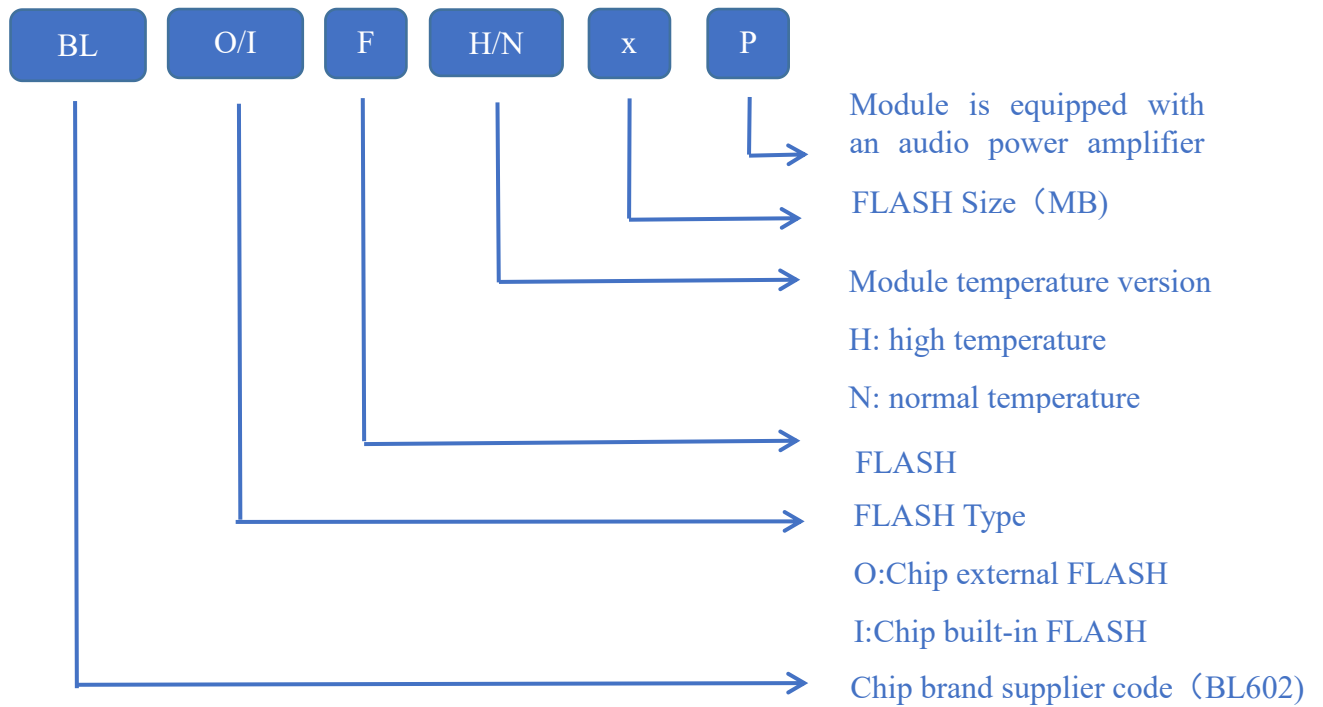


Figure 5 Shielding cover silk screen representative information

4. Pin Definition

Ai-WV01-32S module has a total of 40 pins, as shown in the pin diagram. The pin function definition table is the interface definition.

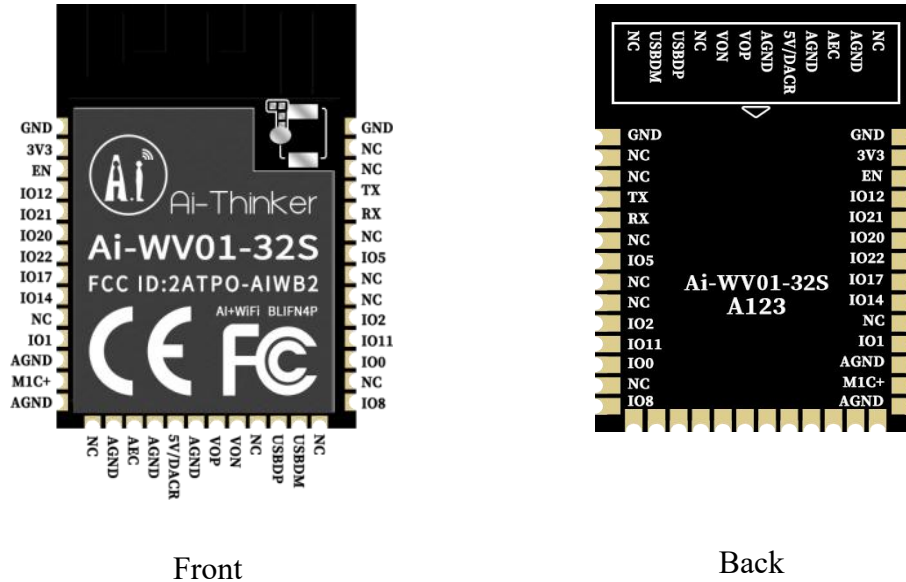


Figure 6 Pin diagram

Table 6 Pin function definition table

No.	Name	Function
1	GND	Grounding
2	3V3	Chip power supply pin, 3.3V power supply; external power supply current is recommended to be above 500mA
3	EN	The default is to enable the chip, high level is valid, and it cannot be used at the same time as RST
4	IO12	SPI_MOSI /I2C_SCL/PWM_CH2/ADC_CH0/SWGPI012/TMS
5	IO21	SF1_CS/SF2_CS /SPI_MISO/I2C_SDA/PWM_CH1/SWGPI021/TDI
6	IO20	GPIO20/SPI_MOSI/MISO/IIC_SCL/PWM_CH0/JTAG_TMS/TCK
7	IO22	GPIO22/SPI_SS/IIC_SCL/PWM_CH2/JTAG_TCK/TMS
8	IO17	GPIO17/SPI_MOSI/MISO/IIC_SDA/PWM_CH2
9	IO14	GPIO14/SPI_SS/IIC_SCL/PWM_CH4/ADC_CH2
10	NC	Dangling

11	IO1	GPIO1/SPI_MOSI/MISO/IIC_SDA/PWM_CH1
12	AGND	AGND; it is recommended to connect to the negative terminal of the microphone input
13	MIC+	Microphone input positive terminal
14	AGND	Analog Ground
15	NC	Dangling
16	AGND	Analog Ground
17	AEC	The default setting is NC. When the module is connected to an external amplifier, this pin can be used as an audio capture input.
18	AGND	Analog Ground
19	5V/DACR	The default is the power supply pin of the built-in amplifier, 5V power supply; the external power supply current is recommended to be above 1A When the module is connected to an external amplifier, this pin is used as the audio DAC output
20	AGND	Analog Ground
21	VOP	The module has a built-in amplifier output P. When the module is connected to an external amplifier, this pin can be left floating.
22	VON	The module has a built-in amplifier output N. When the module is connected to an external amplifier, this pin can be left floating.
23	NC	Dangling
24	USBDP	Default USB Negative Data (pull down) for the VB6824 chip Other functions (UART1RXD: Uart1 Data In(D); SPI2DOB: SPI2 Data Out (B); IIC_SDA_A: IIC SDA(A); (pull down)
25	USBDM	Default USB Positive Data (pull down) for the VB6824 chip Other functions (UART1TXD: Uart1 Data Out(D); SPI2CLKB: SPI2 Clock (B); IIC_SCL_A: IIC SCL(A); ADC12: ADC Input Channel 12)
26	NC	Dangling

27	IO8	As a bootstrap, when it is high at the moment of power-on, the module enters the burning mode; when it is low at the moment of power-on, the module starts normally.
28	NC	Dangling
29	IO0	GPIO0/SDIO_CLK/SPI_MOSI/MISO/IIC_SCL/PWM_CH0/JTAG_TMS/TCK
30	IO11	GPIO11/SPI_SCLK/IIC_SDA/ADC_CH10
31	IO2	GPIO2/SPI_SS/IIC_SCL/PWM_CH2
32	NC	Dangling
33	NC	Dangling
34	IO5	GPIO5/SPI_MOSI/MISO/IIC_SDA/PWM_CH0/ADC_CH4
35	NC	Dangling
36	RX	RXD/GPIO7/SPI_SCLK/IIC_SDA/PWM_CH2/JTAG_TDO/TDI
37	TX	TXD/GPIO16/SPI_MOSI/MISO/IIC_SCL/PWM_CH1/JTAG_TMS/TCK
38	NC	Dangling
39	NC	Dangling
40	GND	Grounding

Annotation:

1. This module has a built-in audio amplifier by default. If an external amplifier is required, please contact Anxinke for a customized BOM. In addition, when an external amplifier is installed, the functions of some pins will change. See the pin definitions in this table for details.
2. GPIO8 is used as the Bootstrap pin. When it is high at the moment of power-on, the module enters the programming mode. When it is low at the moment of power-on, the module starts normally.
3. In PWM lighting control applications, the IO pins generating PWM must maintain a stable state (typically low) during power-up to avoid flickering. During or after power-up, GPIOs 0-2, 5, 7, 14, and 20-22 may have a weak pull-up, resulting in a high level. These pins can be pulled down by adding a 4.7k Ω resistor to maintain a low level.
4. The default function of GPIO11 is JTAG TDO. It may output a high level during power-on and is not recommended for PWM light control.

5. Schematic

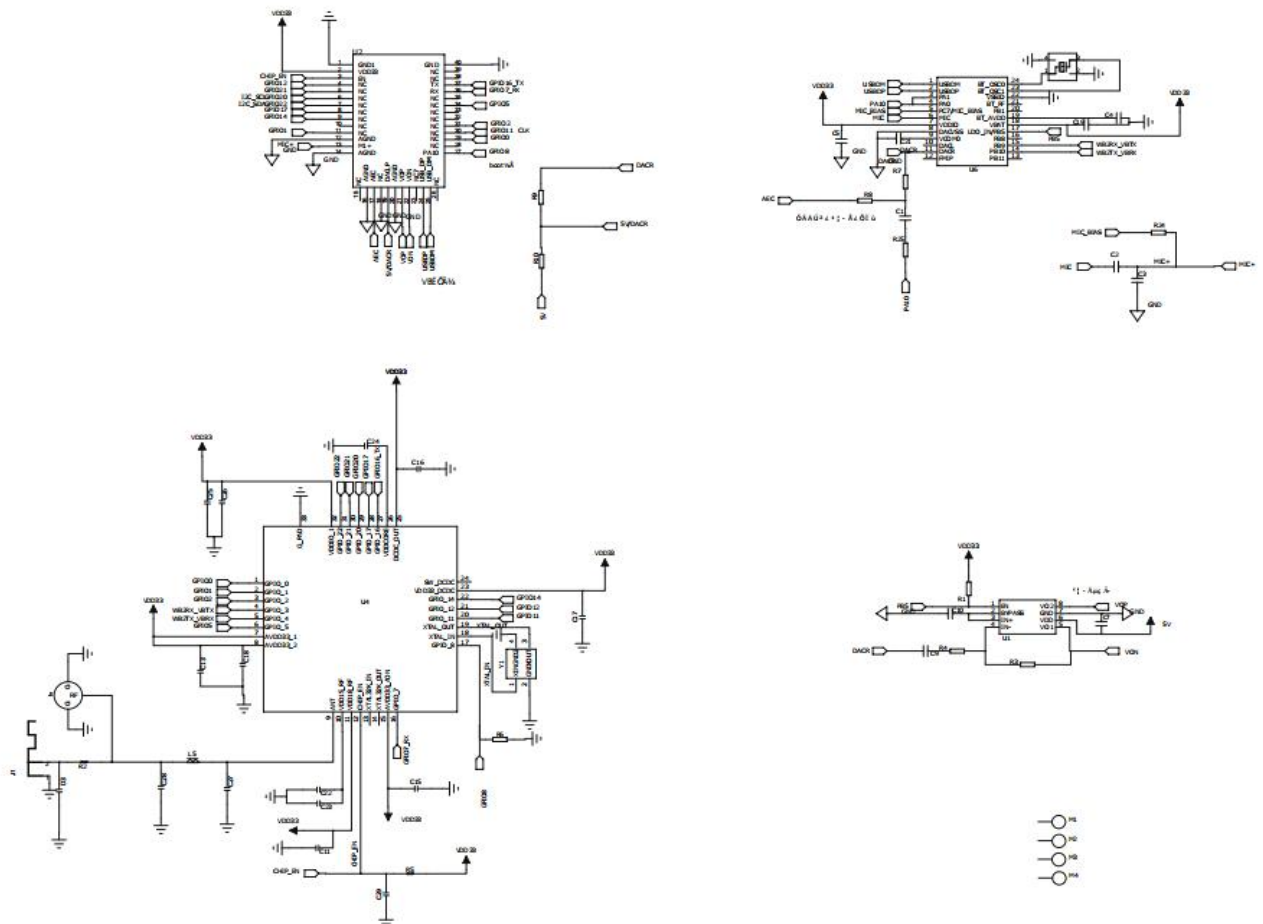


Figure 7 Schematic diagram

6. Antenna parameters

6.1. Antenna test prototype illustration

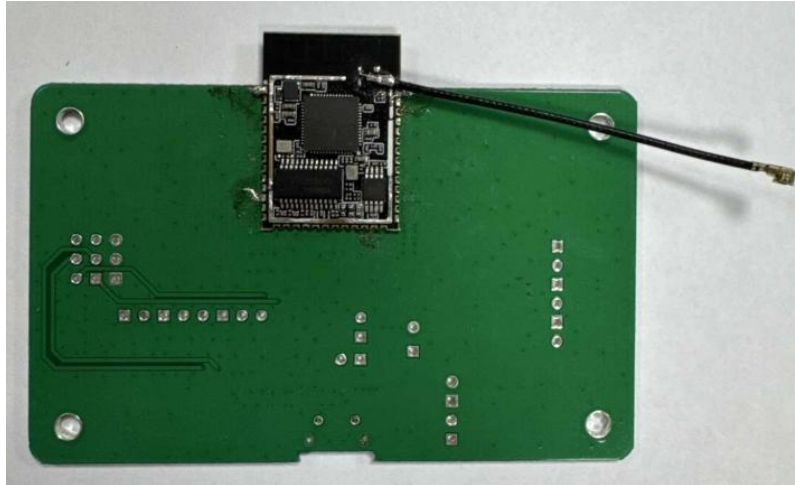


Figure 8 Antenna test prototype reference diagram antenna

6.2. Antenna S parameters

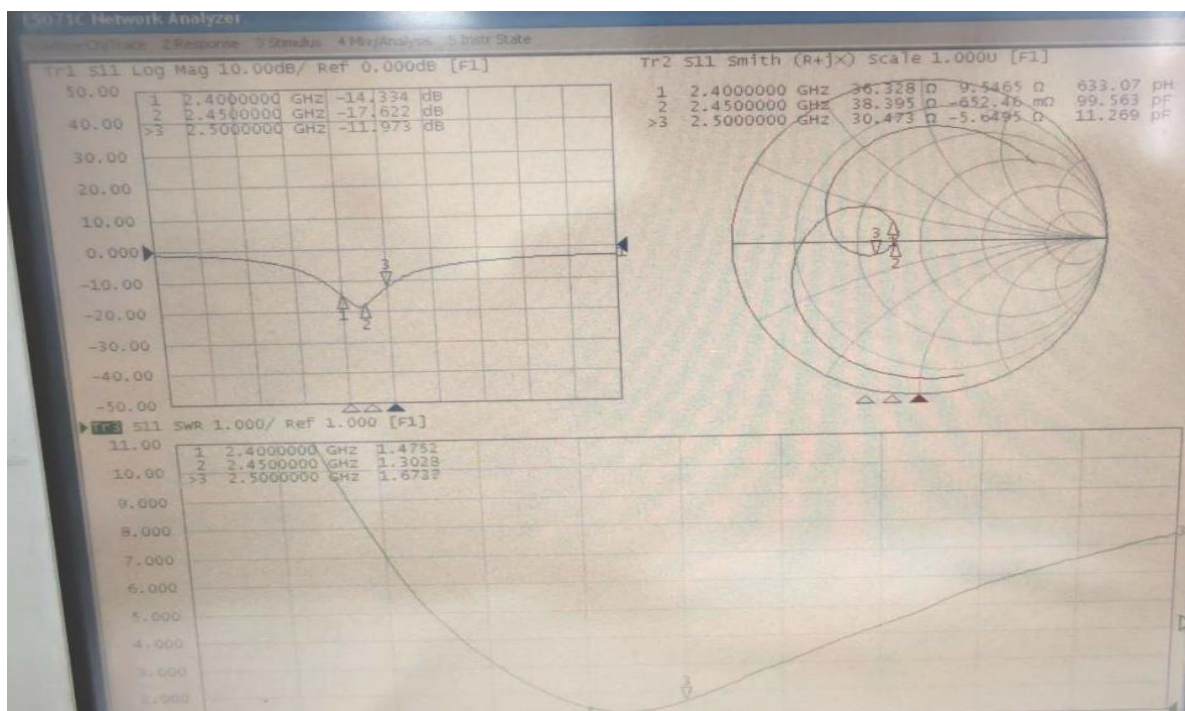


Figure 9 Antenna S parameters

6.3. Antenna gain and efficiency

Table 7 Antenna gain and efficiency

Frequency ID	1	2	3	4	5	6	7	8	9	10	11
Frequency(MHz)	2400	2410	2420	2430	2440	2450	2460	2470	2480	2490	2500
Gain (dBi)	1.08	1.11	1.17	1.15	1.27	1.40	1.34	1.24	1.07	0.95	0.86
Efficiency (%)	59.86	61.01	62.17	62.33	62.33	63.00	62.19	61.43	60.41	60.20	58.28

6.4. Antenna pattern

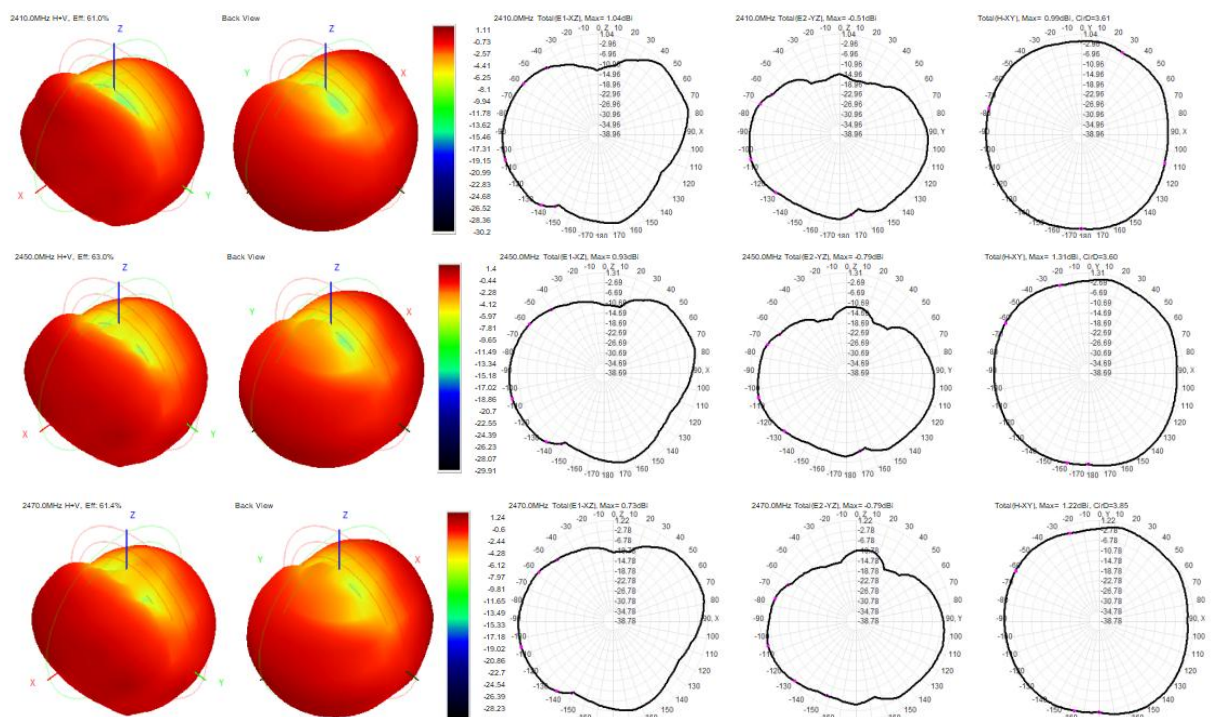


Figure 10 Antenna pattern

7.2. Recommended PCB package size

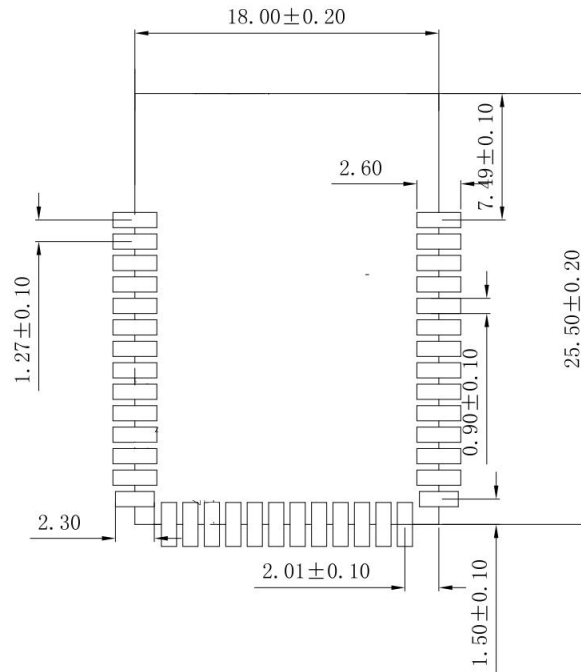


Figure 12 Recommended PCB package dimensions

7.3. Antenna layout requirements

- The following two methods are recommended for the installation position on the motherboard:

Solution 1: Place the module on the edge of the motherboard, with the antenna area extending beyond the edge.

Solution 2: Place the module on the edge of the motherboard and hollow out an area on the edge of the motherboard where the antenna is located.

- To ensure the performance of the onboard antenna, no metal parts should be placed around the antenna, and it should be kept away from high-frequency devices.

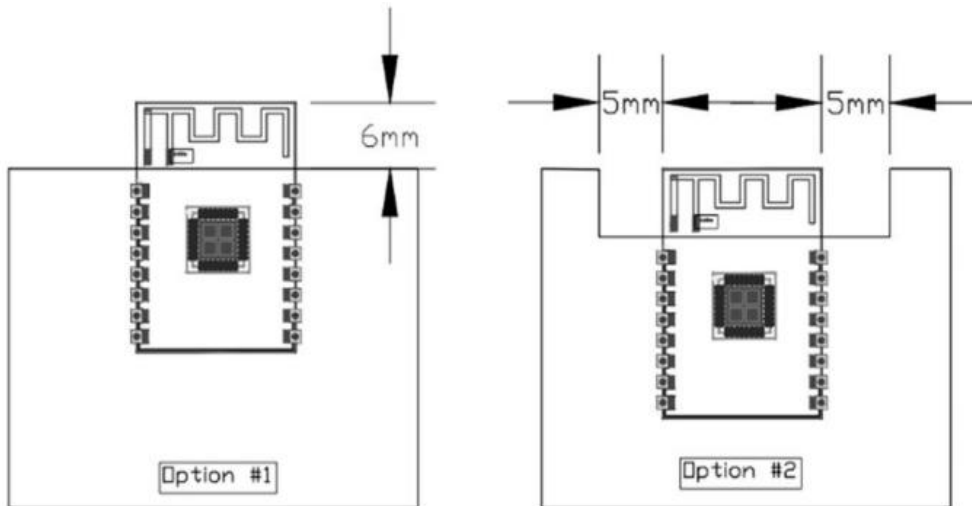


Figure 13 Antenna layout diagram

7.4. Power supply

- Recommended chip uses a 3.3V voltage and a peak current of more than 500mA .
- It is recommended that the built-in PA use a 5V voltage and a peak current of more than 1A .
- If using a DC-DC converter, it is recommended that the ripple be controlled within 3 % .
- It is recommended to reserve space for dynamic response capacitors in the DC-DC power supply circuit to optimize the output ripple when the load changes greatly.
- It is recommended to add ESD devices to the power interface.

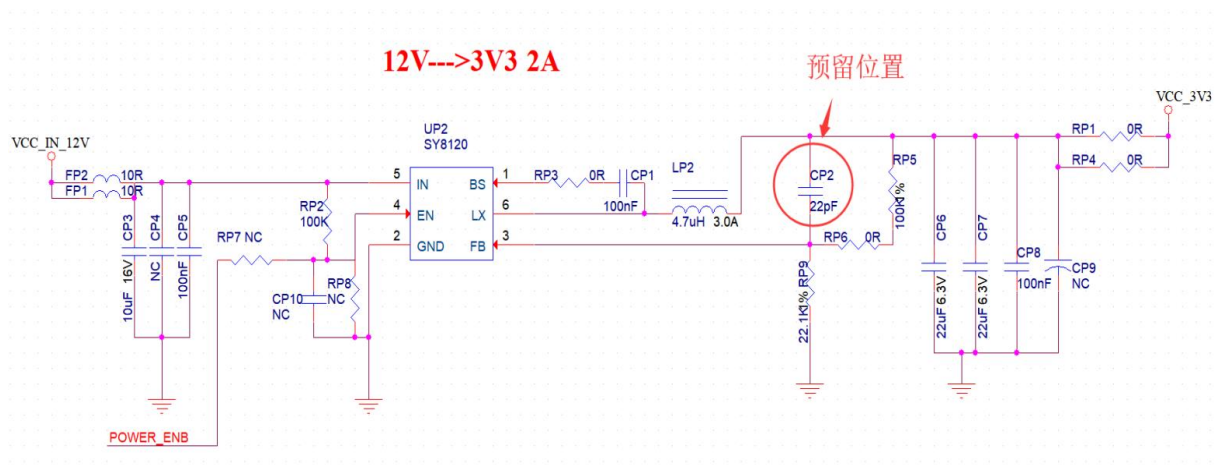


Figure 14 DC-DC buck reference circuit diagram

7.5. GPIO

- The module has some external IO ports. If you need to use them, it is recommended to connect a 10-100 ohm resistor in series with the IO port. This can suppress overshoot and make the voltage level on both sides more stable. It also helps with EMI and ESD.
- For the pull-up and pull-down functions of special IO ports, please refer to the instructions in the datasheet, as this will affect the startup configuration of the module.
- The IO port of the module is 3.3V. If the voltage levels of the main control and module IO ports do not match, a level conversion circuit needs to be added.
- If the IO port is directly connected to a peripheral interface, or terminals such as a pin header, it is recommended to reserve ESD devices near the terminals where the IO port is routed.

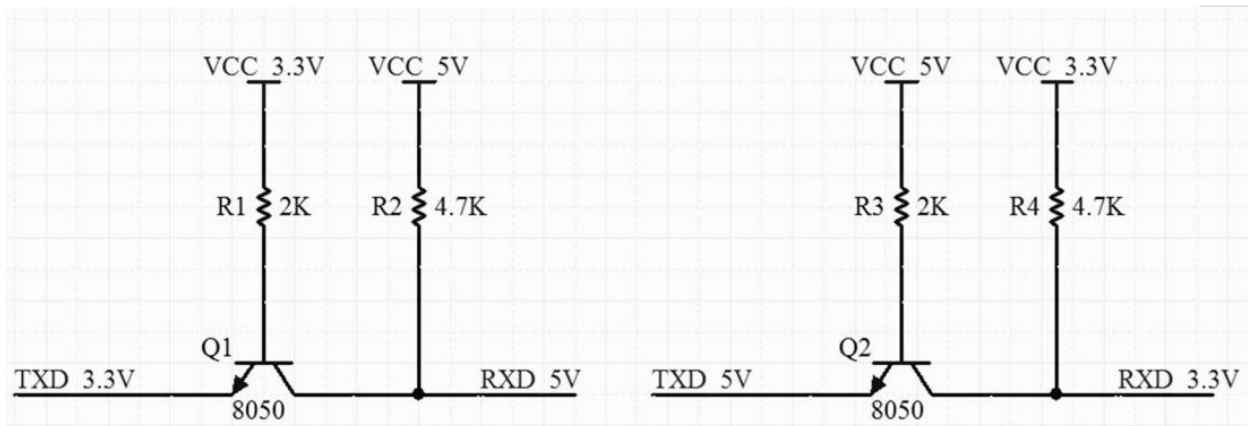


Figure 15 Level conversion circuit

8. Storage conditions

Products sealed in moisture-proof bags should be stored in a non-condensing atmosphere <40° C/90%RH.

The module's moisture sensitivity level MSL is level 3.

After the vacuum bag is unsealed, it must be used within 168 hours at 25±5°C/60%RH. Otherwise, it needs to be baked before it can be used again.

9. Reflow Oven Profile

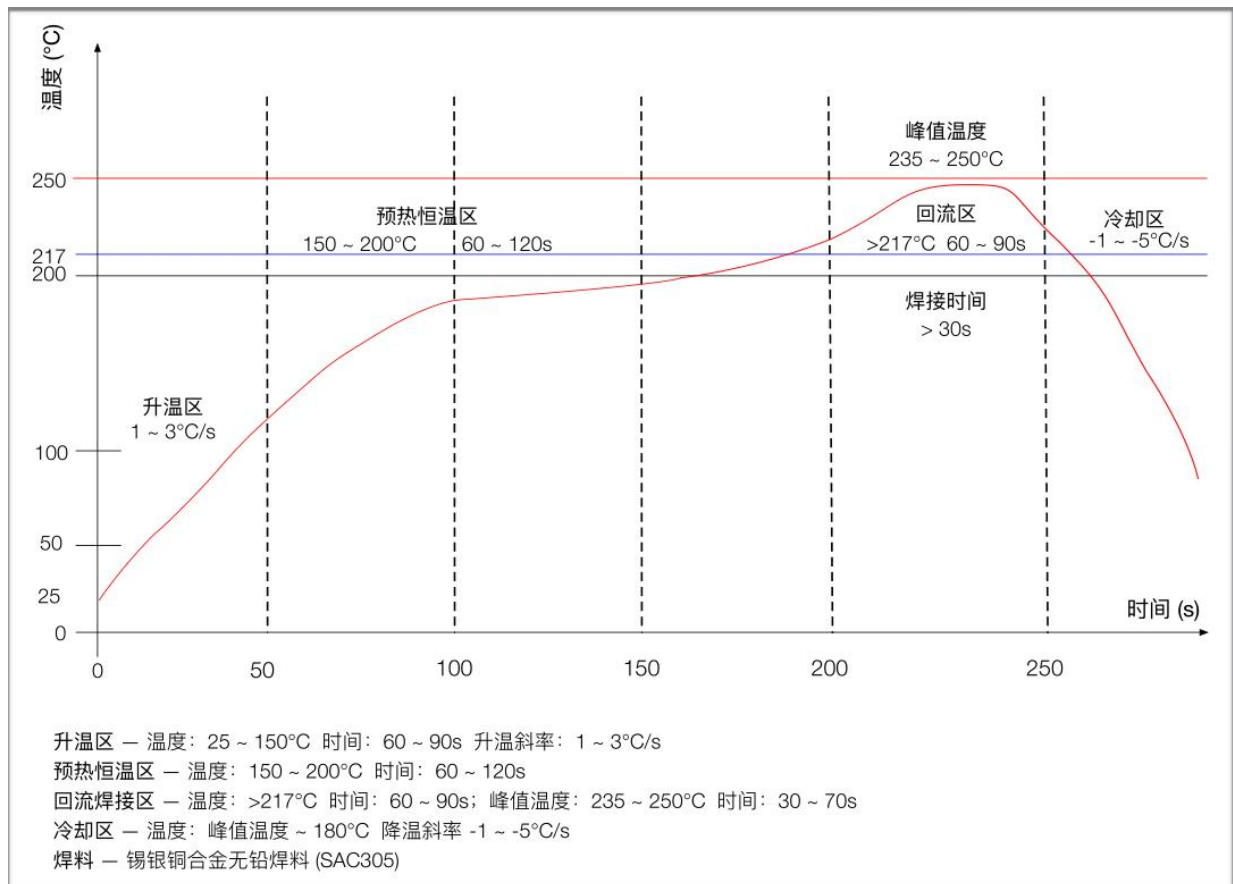


Figure 16 Reflow soldering curve

10. Product packaging information

Ai-WV01-32S module is packaged in tape, 800 pcs/reel. As shown below:



Figure 17 Packaging Taping Diagram

11. Contact Us

[Ai-Thinker official website](#)

[Office forum](#)

[Develop DOCS](#)

[LinkedIn](#)

[Tmall shop](#)

[Taobao shop](#)

[Alibaba shop](#)

Technical support email: support@aithinker.com

Domestic business cooperation: sales@aithinker.com

Overseas business cooperation: overseas@aithinker.com

Company Address: Room 403-405, 408-410, Block C, Huafeng Smart Innovation Port, Gushu 2nd Road, Xixiang, Baoan District, Shenzhen.

Tel: +86-0755-29162996



WeChat mini program



WeChat official account

Disclaimer and Copyright Notice

Information in this document, including URL references, is subject to change without notice.

This document is provided "as is" without warranty of any kind, including any warranty of merchantability, fitness for a particular purpose, or non-infringement, and any warranty otherwise expressly stated in any proposal, specification, or sample. No liability is assumed with respect to this document, including liability for infringement of any patent arising from the use of the information in this document. No license, express or implied, by estoppel or otherwise, to any intellectual property right is granted by this document.

The test data obtained in this article are all obtained from the Anxinke laboratory test, and the actual results may vary slightly.

All trade names, trademarks and registered trademarks mentioned herein are the property of their respective owners and are hereby acknowledged.

The final right of interpretation belongs to Shenzhen Anxinke Technology Co., Ltd.

Notice

The contents of this manual may be changed due to product version upgrades or other reasons.

Shenzhen Anxinke Technology Co., Ltd. reserves the right to modify the contents of this manual without any notice or reminder.

This manual is for use as a guide only. Shenzhen Anxinke Technology Co., Ltd. makes every effort to provide accurate information in this manual. However, Shenzhen Anxinke Technology Co., Ltd. does not ensure that the contents of this manual are completely error-free, and all statements, information and suggestions in this manual do not constitute any express or implied warranty.

Important Notice

Essence provides technical and reliability data (including datasheets), design resources (including reference designs), applications or other design advice, web tools, safety information and other resources (hereinafter referred to as "these resources") "as is" without guarantee of defects and without warranty of any kind, either express or implied, including but not limited to, express or implied warranties of fitness for a particular purpose or non-infringement of any third party intellectual property rights. Essence specifically disclaims any liability for any consequential or incidental damages, including but not limited to, damages arising from the application or use of any of its products and circuits.

Essence reserves the right to change the information published in this document (including but not limited to indicators and product descriptions) and any of the company's products involved without prior notice. This document automatically replaces and replaces all information provided in the previous version of the document with the same document number.

These resources are available to experienced developers designing with Essence products. You are solely responsible for: (1) selecting the appropriate Essence products for your application; (2) designing, validating, and operating your application and product throughout its lifecycle; and (3) ensuring that your application meets all applicable standards, specifications, and laws, as well as any other functional safety, information security, regulatory, or other requirements.

Essence authorizes you to use these resources solely for the research and development of applications for Essence products described herein. Without Essence's permission, no entity or individual may excerpt or copy these resources, in whole or in part, or disseminate them in any form. You have no right to use any other Essence intellectual property or any third-party intellectual property. You shall fully indemnify Essence and its representatives for any claims, damages, costs, losses, and liabilities arising from the use of these resources, and Essence shall not be liable for any such claims.

Products provided by Essence are subject to Essence's terms of sale or other applicable terms accompanying Essence products. Essence's provision of these resources does not extend or otherwise change the warranty or warranty disclaimer applicable to the product release.